

## ABSTRACT OF THE DISCLOSURE

In a lead forming apparatus for a semiconductor device according to the invention, a holder holds a semiconductor device to be formed, the semiconductor device having leads  
5 extending from a package thereof. Two die assemblies (for bending, for cutting or the like) are set in parallel, each comprising a pair of top and bottom dies matched with each other. A mover changes a relative distance between the two die assemblies. The top and bottom dies in the two die  
10 assemblies are positioned to interpose the leads of the semiconductor device held on said holder and form the leads between them.